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- Members of the Texas Instruments
 Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Impedance State During Power Up and Power Down
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), 300-mil Shrink Small-Outline (DL) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16843 18-bit bus-interface D-type latches are designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The 'ABT16843 can be used as two 9-bit latches or one 18-bit latch. The 18 latches are transparent D-type latches. The device provides true data at its outputs.

A buffered output-enable (\overline{OE}) input can be used to place the nine outputs in either a normal logic state (high or low logic levels) or a high-impedance state. The outputs are in the high-impedance state during power up and power down. The outputs remain in the high-impedance state while the device is powered down. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

SN54ABT16843 . . . WD PACKAGE SN74ABT16843 . . . DGG OR DL PACKAGE (TOP VIEW)

	Г		1		1	
1CLR	d	1	\cup	56	b	1LE
10E	d	2		55	þ	1PRE
1Q1	d	3		54	þ	1D1
GND	D	4		53	1	GND
1Q2	D	5		52	1	1D2
1Q3	q	6		51	1	1D3
V_{CC}	q	7		50	1	V_{CC}
1Q4	q	8		49	1	1D4
1Q5	Q	9		48	0	1D5
1Q6	Q	10		47	0	1D6
GND	Q	11		46	0	GND
1Q7	q	12		45	0	1D7
1Q8	q	13		44	0	1D8
1Q9	q	14		43	0	1D9
2Q1	q	15		42	0	2D1
2Q2	9	16		41	0	2D2
2Q3	Q	17		40	р	2D3
GND	Q	18		39	Р	GND
2Q4	q	19		38	0	2D4
2Q5	9	20		37	0	2D5
2Q6	3	21		36	P	2D6
V_{CC}	_	22		35	P	V_{CC}
2Q7	Ц	23		34	P	2D7
2Q8	Ц	24		33	[2D8
GND	3	25		32	ħ	GND
200	9	26		31	Į	2D9
20E	Ц	27		30	Į	2PRE
2CLR	4	28		29	Ц	2LE



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description (continued)

OE does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

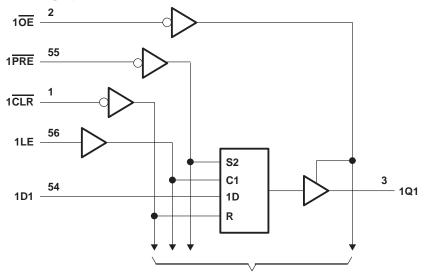
The SN54ABT16843 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16843 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE (each 9-bit latch)

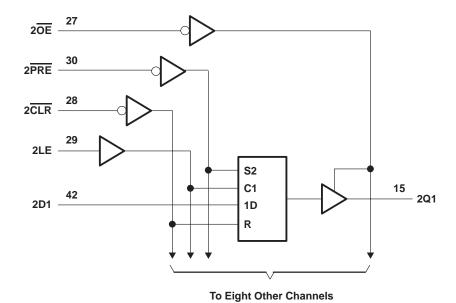
	(Guerra Britanerry										
	INPUTS										
PRE	CLR	ŌĒ	LE	D	Q						
L	Х	L	Х	Χ	Н						
Н	L	L	X	Χ	L						
Н	Н	L	Н	L	L						
Н	Н	L	Н	Н	Н						
Н	Н	L	L	Χ	Q ₀						
Х	Χ	Н	Χ	Χ	Z						



logic diagram (positive logic)



To Eight Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16843	96 mA
SN74ABT16843	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{Stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54AB1	16843	SN74AB1	Γ16843	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	V _{CC} Supply voltage				4.5	5.5	V
VIH	High-level input voltage		2	Z	2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage			Vcc	0	VCC	V
IOH	High-level output current		1	-24		-32	mA
l _{OL}	Low-level output current		3	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	20/	10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate	·	200		200	·	μs/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	ARAMETER	TEST	ONDITIONS	T,	_A = 25°C	;	SN54AB	Γ16843	SN74AB1	16843	UNIT	
	ARAMETER	TEST C	ONDITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -3 \text{ mA}$					2.5		2.5			
\/a		V _{CC} = 5 V,	3			3		3		V		
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
VOL		V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$			0.55		0.55			V	
VOL		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$	0.55*				0.55		V		
V _{hys}					100						mV	
lį		$V_{CC} = 0$ to 5.5 $V_{I} = V_{CC}$ or GN				±1		±1		±1	μΑ	
l _{OZPU} :	‡	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \overline{OE} = X$				±50		±50		±50	μΑ	
lozpd:	‡	$V_{CC} = 2.1 \text{ V to } 0,$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \overline{OE} = X$				±50	6	±50		±50	μΑ	
lozh		V _{CC} = 2.1 V to V _O = 2.7 V, OE			10	2008	10		10	μΑ		
lozL		$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$ $V_{O} = 0.5 \text{ V}, \overline{OE} \ge 2 \text{ V}$				-10	Q'	-10		-10	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 V$			±100				±100	μΑ	
ICEX	Outputs high	$V_{CC} = 5.5 \text{ V},$	$V_0 = 5.5 V$			50		50		50	μΑ	
ΙΟ§		$V_{CC} = 5.5 \text{ V},$	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
	Outputs high		0			0.5		0.5		0.5		
Icc	Outputs low	$V_{CC} = 5.5 \text{ V, I}_{C}$ $V_{I} = V_{CC} \text{ or GN}$				85		85		85	mA	
	Outputs disabled	1 100 31 31				0.5		0.5		0.5		
ΔICC¶		V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5	mA	
Ci		V _I = 2.5 V or 0.5 V			3.5						pF	
Co		V _O = 2.5 V or 0.5 V			8						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] This parameter is characterized, but not production tested.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $[\]P$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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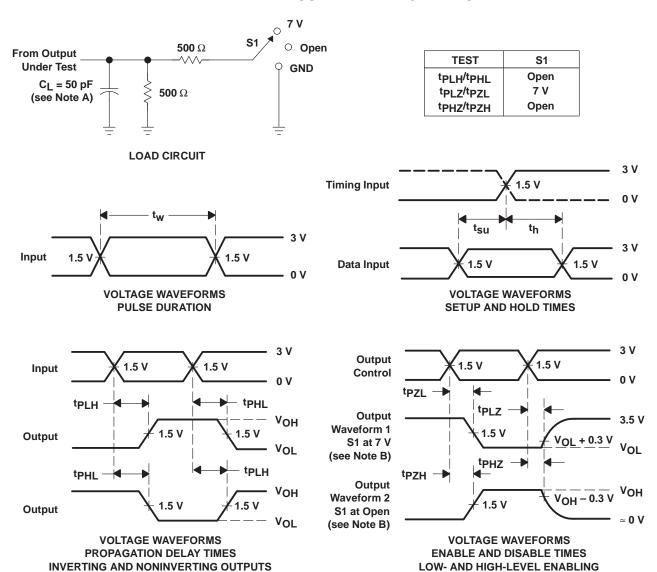
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V _{CC} =	V _{CC} = 5 V, T _A = 25°C		SN54ABT16843		Г16843	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
		CLR low	3.3		3.3	À	3.3			
t _W	Pulse duration	PRE low	3.3		3.3	Z	3.3		ns	
	LE high				3.3	77	3.3			
	Setup time, data before LE↓	High	0.9		0.9	,	0.9		no	
t _{su}	Setup time, data before LEV	Low	0.6		0.6		0.6		ns	
tı.	Hold time, data after LE↓	High	1.7		01.7		1.7		ns	
t _h	Hold time, data after LLV	Low	1.8		1.8		1.8			

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT16843		SN74ABT16843		UNIT
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	D	Q	1.6	3.1	4.2	1.6	5.1	1.6	4.8	ns
^t PHL	Ь	ά	1.6	3.2	4.2	1.6	5	1.6	4.8	115
^t PLH	LE	Q	2.3	4	5	2.3	6.3	2.3	5.9	20
^t PHL	LE	ά	2.5	3.9	4.8	2.5	5.6	2.5	5.3	ns
^t PLH	PRE	Q	2.1	4	5.1	2.1	6.3	2.1	6.1	ns
^t PHL	PRE	ď	2.2	3.7	4.6	2.2	5.3	2.2	5	113
^t PLH	CLR	Q	1.9	3.7	4.8	1.9	5.7	1.9	5.4	no
t _{PHL}	CLR	ά	2.2	4.2	5.3	2.2	6.1	2.2	6	ns
^t PZH	ŌĒ	Q	1.6	3.3	4.3	2 1.6	5.5	1.6	5.4	200
t _{PZL}	OE	γ	2	3.2	4.6	2	5.9	2	5.8	ns
^t PHZ	ŌĒ	Q	1.7	4	5.5	1.7	6.4	1.7	6.3	ne
^t PLZ	OE .	y	1.7	3.7	4.4	1.7	5.3	1.7	5.2	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

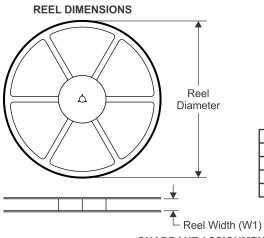
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

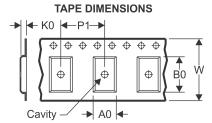
Figure 1. Load Circuit and Voltage Waveforms

PACKAGE MATERIALS INFORMATION

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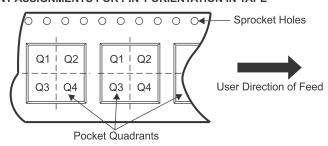
TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
E	30	Dimension designed to accommodate the component length
K	(0	Dimension designed to accommodate the component thickness
	Ν	Overall width of the carrier tape
F	21	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16843DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16843DLR	SSOP	DL	56	1000	367.0	367.0	55.0

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